



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2812
#5/Re-Amend A
Diking
10/22/01

Application of

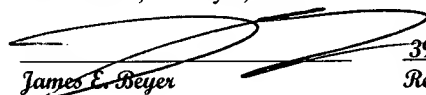
X Applicants : Salman Akram and Mike Brooks
Serial No. : 09/804,051 ✓
Filed : March 12, 2001
Title : MULTIPLE DIE PACKAGE
Docket No. : MIO 0069 PA
Confirm No. : 7513
Art Unit : 2812

RECEIVED
JUL 12 2001
10 2300 HALL ROOM

Assistant Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on July 6, 2001.


James E. Beyer 39,564
Reg. No.

Sir:

PRELIMINARY AMENDMENT

In the Specification:

Please replace the first heading and paragraph of page 1 (lines 3-7) with the following new paragraph:

A1

CROSS-REFERENCE TO RELATED APPLICATIONS

The present application is related to U.S. Patent Application Serial Nos. 09/804,421 DIE STACKING SCHEME, filed March 12, 2001 and 09/ 855,731 SEMICONDUCTOR/PRINTED CIRCUIT BOARD ASSEMBLY, AND COMPUTER SYSTEM, filed May 15, 2001.